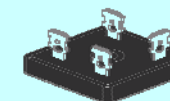


**MATERIAL COMPOSITION DECLARATION**

Supplier: Fagor Electrónica S. Coop

Package: FB Fast-on



Part Number:

Description: Power Bridge Rectifier Fast-on

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS( mg)	MATERIAL MASS( %)	ELEMENT NAME COMPOSITION	CAS Nº	ELEMENT % ( BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)	
LEAD FRAME	Copper alloy CuZn15	4.604,730	30,84%	Cu Zn	7440-50-8	85 15	< 2	< 2	< 2	< 2	< 5	< 5	
ENCAPSULATION	Capsule	5.987,350	40,10%	Al	7429-90-5	58,70							
				Fe	7439-89-6	0,24							
				SiO2 (Fused Silica)	60676-86-0	28,7-30,75							
				Polyglycidyl Ether O-Cresol Formaldehyde Novolac	29690-82-2	4,1-6,15	< 2	< 2	< 2	< 2	< 2	< 5	
				Phenolic Resin	9003-35-4	2,05-4,1							
				Sb2O3	1309-64-4	0,41-3,42							
				Brominated Epoxy resin	40039-93-8	0,41-3,42							
	Epoxy Resin & Hardener	4.244,780	28,43%	bis-(epoxiciclohexil)-metilcarboxilato	2386-87-0	20,0-28,0							
				Epoxy resin of bisfenol-A-epiclorhidrina	25068-38-6	10,0-18,0	< 2	< 2	< 2	< 2	< 5	< 5	
				SiO2 (Fused Silica) anhidrido metil-tetrahidroftálico	60676-86-0 26590-20-5	15,0-43,0 27,0-39,0							
CHIP	Doped Silicon Glass Passivated	25,250	0,17%	Si Ni SiO2 PbO2 Al2O3	7440-21-3 7440-02-0 7631-86-9 1309-60-0 1344-28-1	90,6-92,1 0,9-1,3 3,6-3,8 3,4-3,5 0,3-0,5	< 2	22445 (**)	< 2	< 2	< 5	< 5	
SOLDER PASTE	Pb/Sn5 Solder Paste	43,650	0,29%	Pb Sn Sb	7439-92-1 7440-31-5 7440-36-0	92,8 - 95,0 4,5 - 5,5 0,2	< 2	940000 (*)	< 2	< 2	< 5	< 5	
COATING	Electrolitic Nickel	24,240	0,16%		7440-02-0	100	< 2	< 2	< 2	< 2	< 5	< 5	
WHOLE ITEM		14.930,000	100,00%										

Exception according to annex of Directive 2002/95/EC (RoHS):

\* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

\*\* Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes